

(19) World Intellectual Property
Organization
International Bureau



(43) International Publication Date
19 May 2005 (19.05.2005)

PCT

(10) International Publication Number
WO 2005/044364 A1

(51) International Patent Classification⁷: **A61M 37/00**,
B29C 33/42

(21) International Application Number:
PCT/SG2003/000260

(22) International Filing Date:
10 November 2003 (10.11.2003)

(25) Filing Language: English

(26) Publication Language: English

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(81) Designated States (national): AE, AG, AL, AM, AT, AU,
AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU,
CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH,

GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC,
LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW,
MX, MZ, NI, NO, NZ, OM, PH, PL, PT, RO, RU, SC, SD,
SE, SG, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, US,
UZ, VC, VN, YU, ZA, ZM, ZW.

(84) Designated States (regional): ARIPO patent (BW, GH,
GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW),
Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM),
European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE,
ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE,
SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA,
GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Declaration under Rule 4.17:

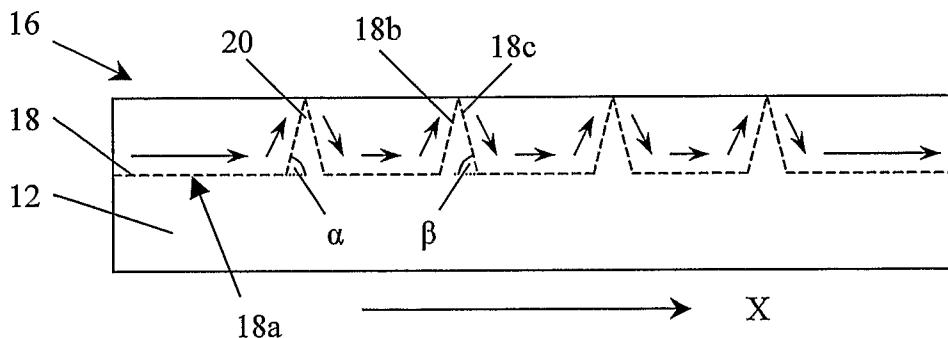
— as to applicant's entitlement to apply for and be granted
a patent (Rule 4.17(ii)) for the following designations AE,
AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA,
CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES,
FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE,
KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD,
MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PH, PL,
PT, RO, RU, SC, SD, SE, SG, SK, SL, TJ, TM, TN, TR, TT,
TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW, ARIPO patent
(BW, GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM,
ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ,
TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK,
EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO,
SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA,
GN, GQ, GW, ML, MR, NE, SN, TD, TG)

Published:

— with international search report

[Continued on next page]

(54) Title: MICRONEEDLES AND MICRONEEDLE FABRICATION



(57) Abstract: A master mould is made by wire cutting a plate in two or more directions to provide a base with an array of master mould needles protruding therefrom. The size and shape of the master mould needles can readily be varied by varying the angles of upward and downward cuts in the two or more directions. The master mould is used to make a secondary mould by hot embossing a secondary mould plate onto the master mould. This forms through-holes in the secondary mould. The secondary mould is plated with a layer of metal, which forms a microneedle array.

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